

Appl. No.: 10/511,792
Reply to Office Action of: 03/27/2007

Amendments to the Specification:

Please delete the paragraph on page 5, lines 19-20 and replace with the following replacement paragraph(s):

- Figure 2: a view in perspective of the underside of an electronic module according to the invention; and
- Figure 3: a cross sectional view of a module tape with a plurality of integrated circuit chips thereon.

Please delete the paragraph on page 9, lines 26-30 and replace with the following replacement paragraph:

Thus in a first mode the mask tape 7 is laid on a substrate tape 2, the chips are placed in cavities 9, as shown in Fig. 3. the As noted above, the chips are preferably mounted after the mask 7 has been deposited on substrate 2, but the chips might also be mounted before the mask is deposited on substrate 2. The chips are coated by filling the holes in the mask, layer 15 is applied and the pre-glued parallelepiped modules are separated. In this case, these layers of glue are preferably layers of hot melt type glue, which may be reactivated by heating.